Title (en)

PLATING METHOD AND APPARATUS THAT CREATES A DIFFERENTIAL BETWEEN ADDITIVE DISPOSED ON A TOP SURFACE AND A CAVITY SURFACE OF A WORKPIECE USING AN EXTERNAL INFLUENCE

Title (de)

PLATTIERUNGSVERFAHREN WELCHES DURCH ÄUSSEREN EINFLUSS EINE SPANNUNGSDIFFERENZ ZWISCHEN EINEM ZUSATZSTOFF AUF EINER HÖHEREN OBERFLÄCHE UND EINER VERTIEFUNG EINES WERKSTÜCKS ERZEUGT UND VORRICHTUNG

Title (fr)

PROCEDE DE METALLISATION CREANT, PAR L'INTERMEDIAIRE D'UNE INFLUENCE EXTERIEURE, UN DIFFERENTIEL ENTRE UN ADDITIF DEPOSE SUR UNE SURFACE SUPERIEURE ET UNE SURFACE CREUSE D'UNE PIECE A USINER

Publication

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Application

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Abstract (en)

[origin: WO0215245A2] The present invention relates to methods and apparatus for plating a conductive material on a substrate surface in a highly desirable manner. The invention removes at least one additive adsorbed on the top portion of the workpiece more than at least one additive disposed on a cavity portion, thereby allowing plating of the conductive material take place before the additive fully re-adsorbs onto the top portion and causing greater plating of the cavity portion relative to the top portion.

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H01L 21/288

IPC 8 full level

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